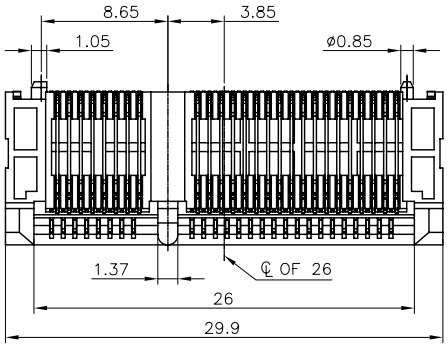
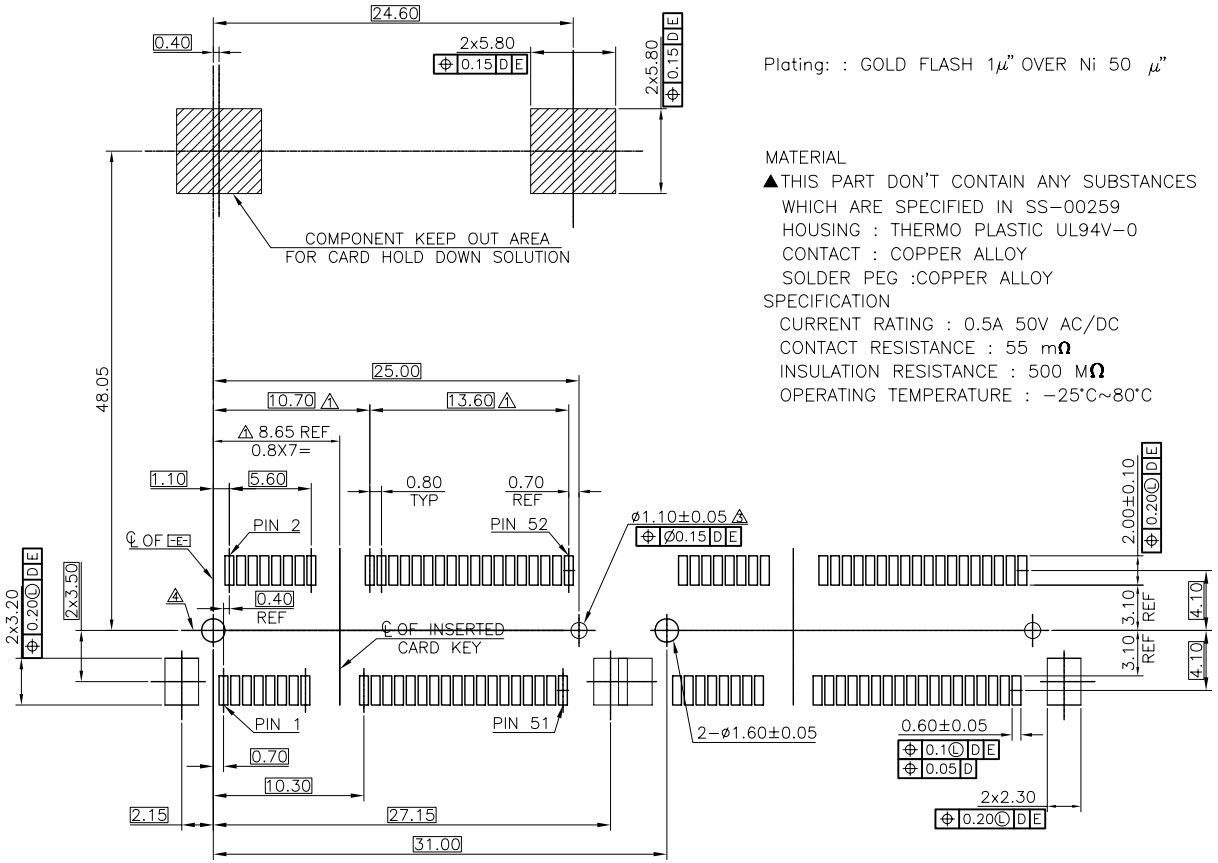
REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	27APR09	JC	BC

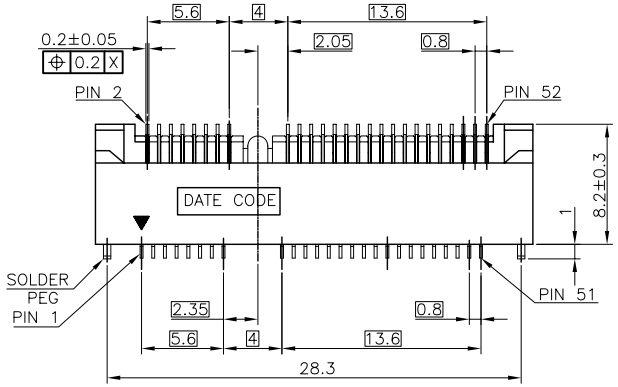


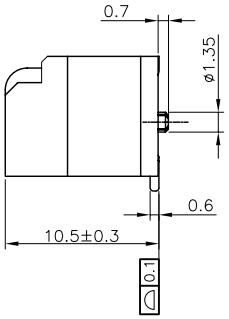


RECOMMENDED P.C.BOARD PATTERN LAYOUT
(SIDE BY SIDE)

Plating: : GOLD FLASH 1μ" OVER Ni 50 μ"

MATERIAL
▲THIS PART DON'T CONTAIN ANY SUBSTANCES
WHICH ARE SPECIFIED IN SS−00259
HOUSING : THERMO PLASTIC UL94V−0
CONTACT : COPPER ALLOY
SOLDER PEG :COPPER ALLOY
SPECIFICATION
CURRENT RATING : 0.5A 50V AC/DC
CONTACT RESISTANCE : 55 mΩ
INSULATION RESISTANCE : 500 MΩ
OPERATING TEMPERATURE : −25˚C~80˚C





GOLD FLASH	J27−0009−01
MIN. GOLD THICKNESS	PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± − 1 PLC ± 0.3 2 PLC ± 0.2 3 PLC ± − 4 PLC ± − ANGLES ± 3˚	DWN JOHN_CHANG 27APR2009	**HAOGUO XING YE SHARE CO.,LTD.**
	CHK MARKS_CHEN 27APR2009	NAME
	APVD BEST_CHANG 27APR2009	0.80MM PITCH MINI PCI EXPRESS H=10.5mm CONNECTOR CUSTOMER DRAWING
MATERIAL SEE NOTE	PRODUCT SPEC	
FINISH SEE NOTE	APPLICATION SPEC	SIZE A3 / DRAWING NO J27−0009 / RESTRICTED TO —
PROJECTION	WEIGHT − GRAMS	
	DIMENSIONS: MM	CUSTOMER DRAWING / SCALE — / SHEET 1 OF 1 / REV 1